



Material Content Data Sheet



Sales Product Name		IDP2303		Issued		20. July 2018		
MA#		MA001623634						
Package		PG-DSO-16-21		Weight*		174.93 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.869	1.64	1.64	16403	16403
leadframe	inorganic material	phosphorus	7723-14-0	0.023	0.01		130	
	non noble metal	zinc	7440-66-6	0.091	0.05		518	
	non noble metal	iron	7439-89-6	1.813	1.04		10362	
wire	non noble metal	copper	7440-50-8	73.601	42.07	43.17	420740	431750
	non noble metal	copper	7440-50-8	0.103	0.06	0.06	589	595
	noble metal	palladium	7440-05-3	0.001	0.00		6	
encapsulation	organic material	carbon black	1333-86-4	0.280	0.16		1599	
	plastics	epoxy resin	-	9.042	5.17		51689	
	inorganic material	silicondioxide	60676-86-0	83.895	47.96	53.29	479588	532876
leadfinish	non noble metal	tin	7440-31-5	1.562	0.89	0.89	8931	8931
plating	noble metal	silver	7440-22-4	0.641	0.37	0.37	3664	3664
glue	plastics	acrylic resin	-	0.222	0.13		1272	
	noble metal	silver	7440-22-4	0.789	0.45	0.58	4509	5781
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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